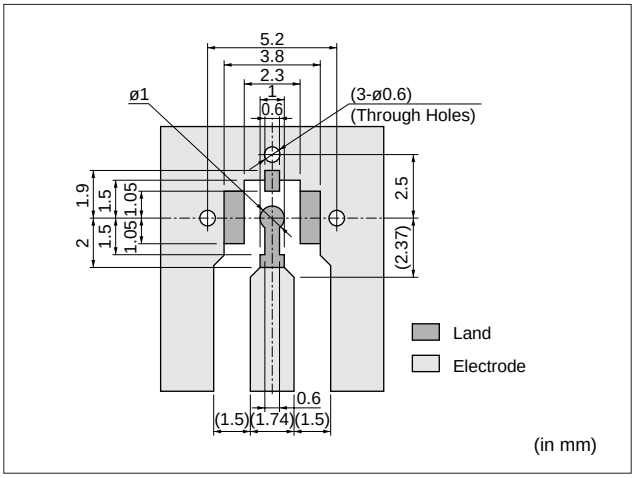
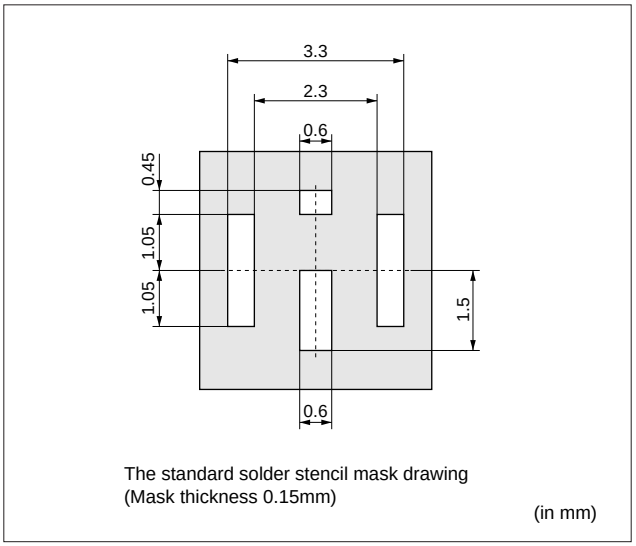
1. Standard pattern dimensions

- I/O pattern should be designed to match 50 ohm impedance circuit.
- Typical PCB material is glass epoxy (εr=4.8). Thickness is 1.0mm
- The solder resist should be printed except for the land pattern on the PCB.



2. Standard solder stencil mask pattern

Follow Standard solder stencil mask pattern to avoid the possibility of solder being trapped under connector.